

SPECIAL ISSUE on FAILURE ANALYSIS

T-DMR will be publishing a special issue in March 2004 comprising selected and expanded papers from the **10th IEEE International Symposium on the Physical and Failure Analysis of Integrated Circuits (IPFA 2003)**. IPFA Symposium is the prime failure analysis and reliability conference in the Asia-Pacific region and papers from research teams in Asia, Europe as well as US are presented at the conference.

Among the topics are:

- Failure mechanisms in Cu - low K metallisation structures
- Gate dielectric breakdown in thin oxides,
- Reliability and failure analysis of Pb free solder joints
- New developments in Failure Analysis tools.

This is an excellent chance to catch up on the latest work in the IC failure mechanism studies.

For details on the special issue contact the Guest Editors

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For more information concerning T-DMR and its EIC and Editors, please visit the T-DMR Web-Site at www.ieee.org/tdmr/

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